



Energy Harvesting Antennas and Circuits for Flexible Electronics

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submissions:

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Message from the Guest Editors

Dear Colleagues,

This Special Issue will focus on the cutting-edge research in academia and industry. It aims to solicit original research and review articles concerning the antenna design, circuit integration and sensing applications of low-power, long-range WSN. A particular focus will be given to the flexible electronics packaging and novel fabrication techniques of the above-mentioned elements. Potential topics include, but are not limited to, the following:

- Rectenna design and rectifiers for energy harvesting.
- Inkjet printing, 3D printing and advanced packaging of flexible antennas.
- Integrated circuits for joint wireless communication, energy harvesting and sensing.
- Flexible electronics, flexible antennas and circuits.
- Wearable electronics, wearable antennas and energy harvesting.
- Advanced fabrication and measurement technology for flexible antennas.
- Practical application of flexible antennas and circuits for energy harvesting.





Editor-in-Chief

Message from the Editor-in-Chief

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